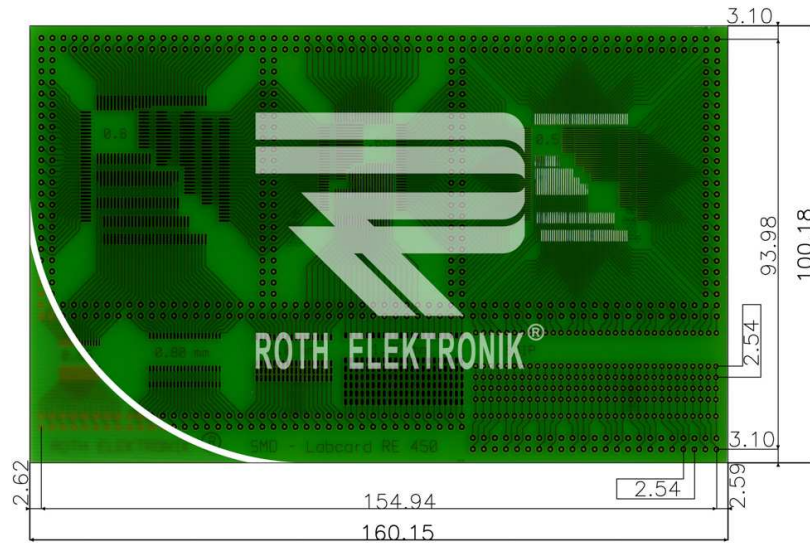


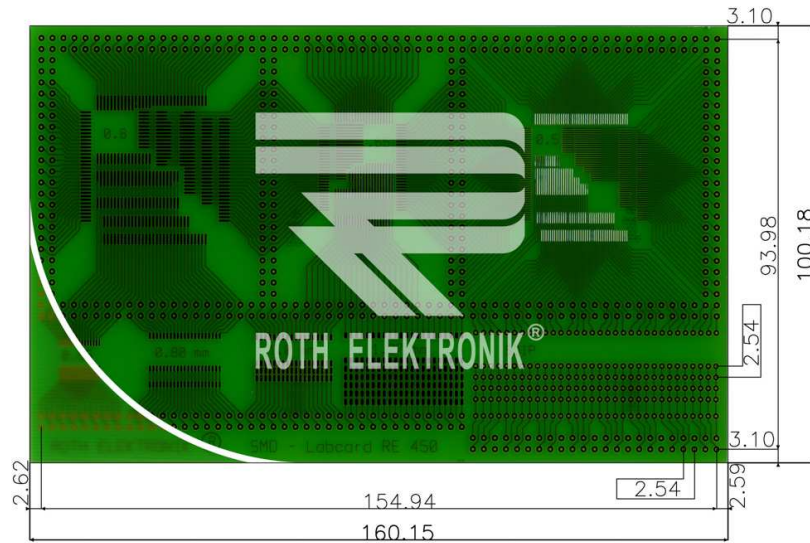
#### RE450-LF

- Epoxy fibre-glass FR4 1.50 mm
- Single-sided 35 µm Cu
- Without holes
- Hot air leveling (HAL-leadfree) with solder stop mask
- Adaption board for approx. 40 different QFP-, SOP-, SSOP-, SDIP-casings:
- QFP- 0.80 mm Pitch: 44, 56, 64, 72, 80, 94, 100, 120-Pin
- QFP- 0.85 mm Pitch: 48, 54, 56, 64, 68, 80, 100-Pin
- QFP- 0.50 mm Pitch: 48, 64, 72, 80, 100, 120, 144, 160-Pin
- SOP- 1.27 mm Pitch: max. 44-Pin in 225, 300, 375, 450, 525, 600 mil.
- SOP- 1.00 mm Pitch: max. 36-Pin in 225, 300, 375 mil.
- SSOP- 0.80 mm Pitch: max. 42-Pin in 300, 450 mil.
- SSOP- 0.65 mm Pitch: max. 30-Pin in 225, 300 mil.
- SDIP- 1.778 mm Raster: max. 64-Pin in 300, 400, 500, 600, 750 mil.
- Size 100 x 160 mm



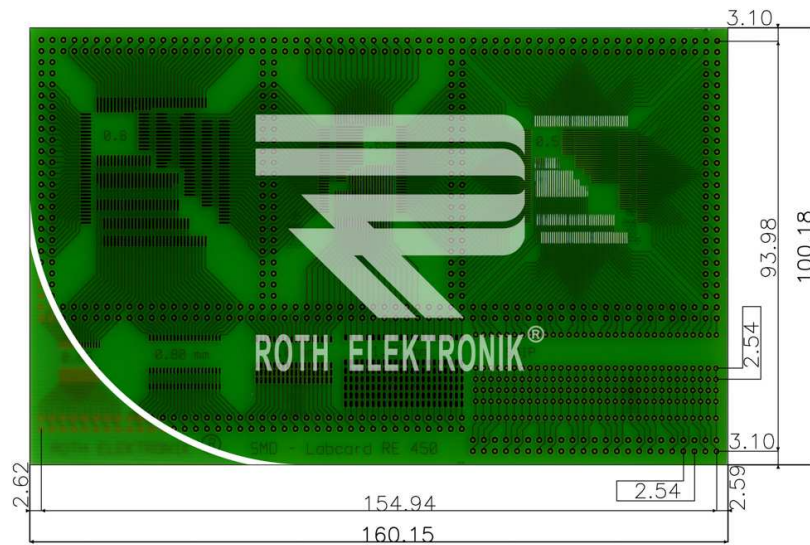
#### RE450-LF

- Epoxydglashartgewebe FR4 1,50 mm
- Einseitig 35 µm Cu
- Ungebohrt
- Heißverzinnt (HAL-leadfree) mit Lötstopplack beschichtet
- Adaptionplatine für ca. 40 verschiedene QFP-, SOP-, SSOP-, SDIP-Gehäuse: QFP 0,80 mm Pitch: 44, 56, 64, 72, 80, 94, 100, 120-Pin QFP 0,85 mm Pitch: 48, 54, 56, 64, 68, 80, 100-Pin QFP 0,50 mm Pitch: 48, 64, 72, 80, 100, 120, 144, 160-Pin SOP 1,27 mm Pitch: max. 44-Pin in 225, 300, 375, 450, 525, 600 mil. SOP 1,00 mm Pitch: max. 36-Pin in 225, 300, 375 mil. SSOP 0,80 mm Pitch: max. 42-Pin in 300, 450 mil. SSOP 0,65 mm Pitch: max. 30-Pin in 225, 300 mil. SDIP 1,778 mm Raster: max. 64-Pin in 300, 400, 500, 600, 750 mil.
- Größe 100 x 160 mm



#### RE450-LF

- Fibre de verre époxyde FR4 1,50 mm
- Simple face 35 µm Cu
- Sans trous
- Étamé à chaud (HAL-leadfree) avec un laque d'arrêt de soudure
- Platine d'adaptation pour 40 boîtiers QFP-, SOP-, SSOP- et SDIP env.
- QFP- 0,80 mm Pitch: 44, 56, 64, 72, 80, 94, 100, 120-Pin
- QFP- 0,85 mm Pitch: 48, 54, 56, 64, 68, 80, 100-Pin
- QFP- 0,50 mm Pitch: 48, 64, 72, 80, 100, 120, 144, 160-Pin
- SOP- 1,27 mm Pitch: max. 44-Pin en 225, 300, 375, 450, 525, 600 mil.
- SOP- 1,00 mm Pitch: max. 36-Pin en 225, 300, 375 mil.
- SSOP- 0,80 mm Pitch: max. 42-Pin en 300, 450 mil.
- SSOP- 0,65 mm Pitch: max. 30-Pin en 225, 300 mil.
- SDIP- 1,778 mm pas: max. 64-Pin en 300, 400, 500, 600, 750 mil.
- Dimensions 100 x 160 mm



#### RE450-LF

- Fibra de vidrio epoxídica FR4 1,50 mm
- Por un lado 35 µm de Cu
- Sin perforación
- Estañado en caliente (HAL-leadfree) y evestido de laca inhibidora de soldadura
- Tarjeta de circuito impreso de adaptación para aprox. 40 distintas carcasas QFP, SOP, SSOP, SDIP QFP- 0,80 mm Pitch: 44, 56, 64, 72, 80, 94, 100, 120-Pin QFP- 0,85 mm Pitch: 48, 54, 56, 64, 68, 80, 100-Pin QFP- 0,50 mm Pitch: 48, 64, 72, 80, 100, 120, 144, 160-Pin SOP- 1,27 mm Pitch: máx. 44 clavijas en 225, 300, 375, 450, 525, 600 mil. SOP- 1,00 mm Pitch: máx. 36 clavijas en 225, 300, 375 mil. SSOP- 0,80 mm Pitch: máx. 42 clavijas en 300, 450 mil. SSOP- 0,65 mm Pitch: máx. 30 clavijas en 225, 300 mil. SDIP- 1,778 mm Raster: máx. 64 clavijas en 300, 400, 500, 600, 750 mil.
- Tamaño 100 x 160 mm